



SOT2106-1

HVQFN98, thermal enhanced very thin quad flat package, no leads, 98 terminals, 0.4 mm pitch, 9 mm x 9 mm x 0.85 mm body

31 March 2020

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN98
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	19-09-2016
Manufacturer package code	MV-A300975-00A

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	8.9	9	9.1	mm
package width	8.9	9	9.1	mm
package height	0.8	0.85	0.9	mm
nominal pitch	-	0.4	-	mm
actual quantity of termination	-	98	-	



HVQFN98, thermal enhanced very thin quad flat package, no leads, 98 terminals, 0.4 mm pitch, 9 mm x 9 mm x 0.85 mm body

2 Package outline

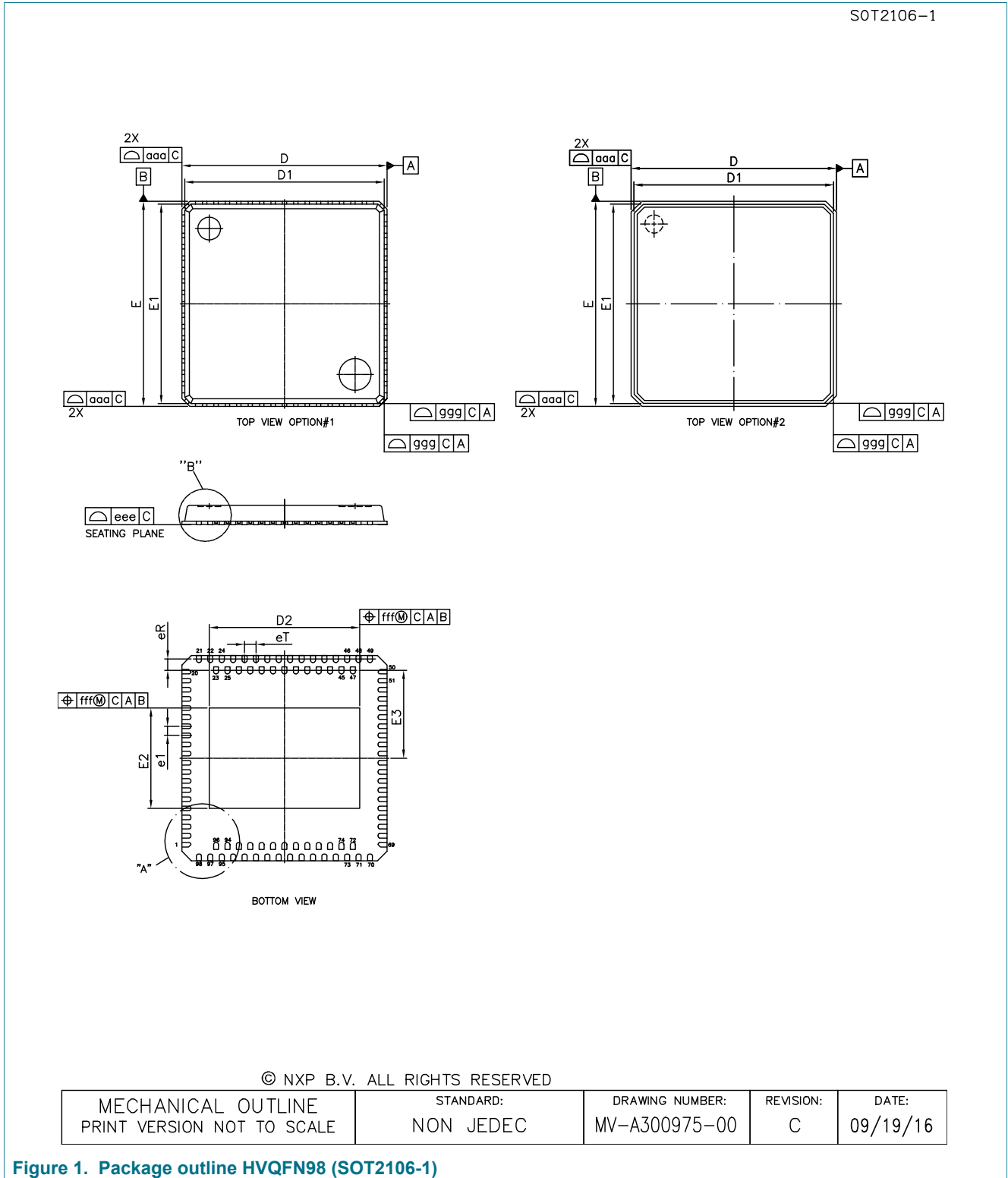
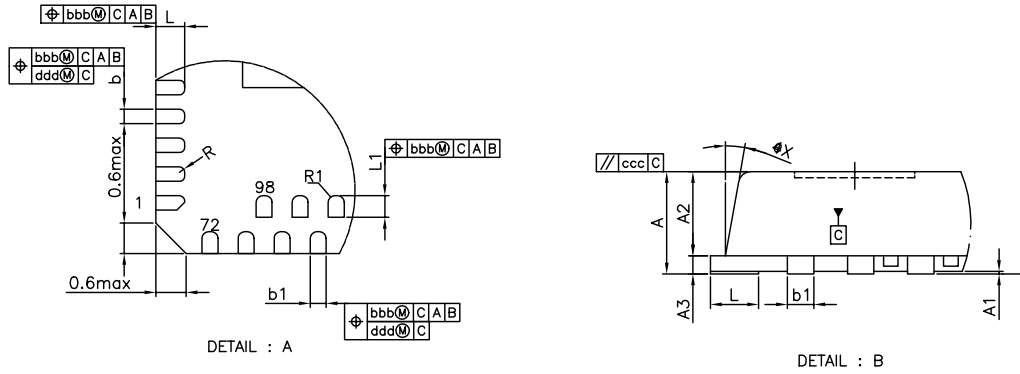


Figure 1. Package outline HVQFN98 (SOT2106-1)

HVQFN98, thermal enhanced very thin quad flat package, no leads, 98 terminals, 0.4 mm pitch, 9 mm x 9 mm x 0.85 mm body

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Symbol	Dimension in mm		
	MIN	NOM	MAX
A	0.80	0.85	0.90
A1	0.00	0.02	0.05
A2	0.65	0.70	0.75
A3	0.15 REF		
b	0.16	0.20	0.28
b1	0.18	0.22	0.30
D/E	8.90	9.00	9.10
D1/E1	8.75 BSC		
D2	6.50	6.60	6.70
E2	4.30	4.40	4.50
E3	3.85 BSC		
eT	0.50 BSC		
eR	0.50 BSC		
e1	0.40 BSC		
L	0.30	0.40	0.50
L1	0.20	0.30	0.40
θ	5°	10°	15°
R	0.08	0.10	0.13
R1	0.09	0.11	0.14
aaa	0.10		
bbb	0.10		
ccc	0.10		
ddd	0.05		
eee	0.08		
fff	0.10		
ggg	0.20		

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MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: MV-A300975-00	REVISION: C	DATE: 09/19/16
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Figure 2. Package outline detail HVQFN98 (SOT2106-1)

3 Legal information

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